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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/784,234  
Filing Date February 14, 2001  
Inventor Shozo Nagano et al.  
Assignee Honeywell International, Inc.  
Group Art Unit 1742  
Examiner Unknown  
Attorney's Docket No. 30-5000-(4015)-Div1  
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating  
Anodes, Metal Alloys For Use as a Conductive Interconnection in an  
Integrated Circuit, and Physical Vapor Deposition Targets

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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References -- See Attached Form PTO-1449

TC 1700

The attached form PTO-1449 is submitted in compliance with  
37 CFR § 1.56. Copies of the cited prior art references are attached. No  
admission is made regarding whether the submitted references are prior art.

This Supplemental Information Disclosure Statement is being filed within  
three months of the filing date of the application or before the mailing of a first  
Office Action, whichever occurs last. Therefore, no fee is believed to be  
required. However, in the event that a fee is required for filing this  
Supplemental Information Disclosure Statement, please charge the fee specified  
under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925.

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Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 6-1-01

By:   
Mark S. Matkin, REG. No. 32,268

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